

Orgalloy® RDG 113 resin is a polyamide designed to be used for refrigerant barrier layer in air conditioning rubber hose.

Packaging:

This grade is delivered dried in sealed packaging (20kg bags) ready to be processed.

Shelf life:

Two years from the date of delivery. For any use above this limit, please refer to our technical services.s.

特性	乾燥/調湿	単位	テスト基準
機械的特性			
引張弾性率	- / 2253	MPa	ISO 527-1/-2
	- / 327000	psi	
降伏応力	- / 47	MPa	ISO 527-1/-2
	- / 6820	psi	
降伏ひずみ	- / 4.4	%	ISO 527-1/-2
破壊呼びひずみ	- / >50	%	ISO 527-1/-2
熱的特性			
溶融温度, 10°C/min	229 / *	°C	ISO 11357-1/-3
その他の特性.			
密度	1120 / 1120	kg/m³	ISO 1183
	1.12 / 1.12	g/cm³	

Processing conditions:

- Drying time (only necessary for bags opened for more than two hours): 4-8 hours at 80-90°C
- Extrusion melt temperature (min-recommended-max): 240-260-300°C

成形加工法	Headquarters:
その他の押出成形	Arkema France 420 rue d'Estienne d'Orves 92705
納入形状	Colombes Cedex France T +33 (0)1 49 00 80 80
ペレット	hpp.arkema.com
領域別の利用可能性	Arkema Inc. – High Performance Polymers
北アメリカ., ヨーロッパ., アジア/太平洋地域., 南・中央アメリカ.	900 First Avenue King of Prussia, PA 19406
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